

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component by laminating a plurality of multi-layered units, each multi-layered unit formed on a support sheet by laminating a release layer, an electrode layer and a ceramic green sheet on ~~a~~the support sheet in this order, the method comprising steps of:

positioning the multi-layered unit on a base substrate so that the surface of the ceramic green sheet is in contact with an agglutinant layer formed on the surface of the base substrate in such a manner that the bonding strength between ~~itself~~the agglutinant layer and the ~~support-base~~ substrate is higher than the bonding strength between the support sheet and the release layer and lower than the bonding strength between ~~itself~~the agglutinant layer and the ceramic green sheet;

pressing it;

peeling the support sheet from the multi-layered unit; and

laminating additional multi-layered units on the base substrate.

2. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the agglutinant layer has a thickness of 0.01 μm to 0.3 μm .

3. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the agglutinant layer contains a binder belonging to the same binder group as that of a binder contained in the ceramic green sheet ~~belongs to~~.

4. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer contains a binder belonging to the same binder group as that of a binder contained in the ceramic green sheet ~~belongs to~~.

5. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the agglutinant layer contains a plasticizing agent belonging to the same plasticizing agent group as that of a plasticizing agent contained in the ceramic green sheet~~belongs to~~.

6. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer contains a plasticizing agent belonging to the same plasticizing agent group as that of a plasticizing agent contained in the ceramic green sheet~~belongs to~~.

7. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the agglutinant layer contains dielectric particles having the same composition as that of dielectric particles contained in the ceramic green sheet.

8. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer contains dielectric particles having the same composition as that of dielectric particles contained in the ceramic green sheet.

9. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the agglutinant layer contains an ampholytic surfactant in an amount smaller than that of ~~the~~ a binder contained in the agglutinant layer.

10. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer contains an ampholytic surfactant in an amount smaller than that of ~~the~~ a binder contained in the agglutinant layer.

11. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the base substrate is formed of a plastic material selected from a group consisting of polyethylene, polypropylene, polycarbonate, polyphenylene ether and polyethylene terephthalate.

12. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the base substrate is formed of a plastic material selected from a group consisting of polyethylene, polypropylene, polycarbonate, polyphenylene ether and polyethylene terephthalate.

13. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the ceramic green sheet has a thickness equal to or thinner than 3 μm .

14. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the ceramic green sheet has a thickness equal to or thinner than 3 μm .

15. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1 which further includes steps of:
peeling off the support sheet from the release layer of the multi-layered unit laminated on the base substrate; and
~~further~~ laminating a new multi-layered unit in which an adhesive layer is formed on the surface of a ceramic green sheet of the new multi-layered unit onto the release layer of the multi-layered unit laminated on the base substrate via the adhesive layer.

16. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2 which further includes steps of:
peeling off the support sheet from the release layer of the multi-layered unit laminated on the base substrate; and
~~further~~ laminating a new multi-layered unit in which an adhesive layer is formed on a ceramic green sheet of the new multi-layered unit onto the release layer of the multi-layered unit laminated on the base substrate via the adhesive layer.

17. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the multi-layered unit includes a spacer layer formed on the surface of the release layer in a complementary pattern to that of the electrode layer.

18. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the multi-layered unit includes a spacer layer

formed on the surface of the release layer in a complementary pattern to that of the electrode layer.